



MEG01-0046C

Application no. 09/837,007

182891

May 18, 2007

TO: Commissioner for Patents  
P. O. Box 1450  
Alexandria, VA 22313-1450

Attn: Art Unit 2891 - Examiner David A Zarneke

FROM: Stephen B. Ackerman, Reg. No. 37,761  
28 Davis Avenue  
Poughkeepsie, N.Y. 12603

SUBJECT: Serial #: 09/837,007  
File Date: April 18, 2001  
Inventor: M.S. Lin, et al.  
Examiner: David A. Zarneke  
Art Unit: 2891  
Title: A Structure and Manufacturing Method of a Chip Scale  
Package

#### RESPONSE TO NON-FINAL OFFICE ACTION

Dear Sir:

The Non-Final Office Action mailed Feb. 22, 2007 has been carefully considered.

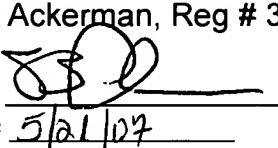
In response thereto, please enter the following amendments and consider the following  
remarks concerning the above-identified application for patent.

#### CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States  
Postal Service as first class mail in an envelope addressed to: Commissioner for Patents,  
P.O. Box 1450, Alexandria, VA 22313-1450, on May 21, 2007.

Stephen B. Ackerman, Reg # 37,761

Signature

  
Date 5/21/07

**Amendments to the Claims** are reflected in the listing of claims which begins on page 3 of this paper.

**Remarks/Arguments** begin on page 6 of this paper.